

ABSTRACT

A film for semiconductor includes a support film, a second adhesive layer, a first adhesive layer and a bonding layer which are laminated together in this order. This film for semiconductor is configured so that it supports a semiconductor wafer laminated on the bonding layer thereof when the semiconductor wafer is diced and the bonding layer is selectively peeled off from the first adhesive layer when a chip is picked up. This film for semiconductor is characterized in that in the case where peel strength at 23°C of the chip is defined as " F_{23} (cN/25mm)" and peel strength at 60°C of the chip is defined as " F_{60} (cN/25mm)", F_{23} is in the range of 10 to 80 and F_{60}/F_{23} is in the range of 0.3 to 5.5. This makes it possible to improve a pickup property of the chip, to thereby prevent generation of defects in a semiconductor element.



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